



Torex...Powerfully Small!

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6203xxxxPR-G

Typical Mass: 53 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.553	Silicon	10400	7440-21-3
		- Arsenic	<1	7440-38-2
Leadframe	24.392	Copper	460200	7440-50-8
		Tin	300	7440-31-5
		Silver	4100	7440-22-4
Die attach	0.126	Silver	2400	7440-22-4
		Epoxy	600	—
Bonding wire	0.069	Gold	1300	7440-57-5
Resin	23.514	Silica	443700	60676-86-0
		Epoxy resin	36200	—
		Phenol resin	26100	—
		Metal hydroxide	7100	—
Plating	0.400	Tin	7500	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."